

Title (en)

Tinning method for copper tubular pieces

Title (de)

Verfahren zur Zinnplattierung von Kupferrohren

Title (fr)

Procédé d'étamage de pièces tubulaires en cuivre

Publication

**EP 1571235 A3 20080319 (FR)**

Application

**EP 05003348 A 20050217**

Priority

FR 0402317 A 20040305

Abstract (en)

[origin: EP1571235A2] The procedure consists of applying an aqueous dispersion of solid tin particles, especially shot, and an agent that partly dissolves the tin, to the surface of a component made from copper or copper alloy, and typically a pipe. The dispersion is applied at a temperature of between 60 - 135 degrees C to form stannic ions that leave a deposit of tin by ion exchange with the copper surface. The dissolving agent is a salt that gives a pH of 3 - 5, e.g. potassium bitartrate, and the aqueous dispersion is circulated for sufficient time to create a layer of tin at least 0.3 mcm and typically 0.5 - 1 mcm thick.

IPC 8 full level

**C23C 18/48** (2006.01); **C23C 18/54** (2006.01)

CPC (source: EP)

**C23C 18/48** (2013.01); **C23C 18/54** (2013.01)

Citation (search report)

- [XY] FR 1056203 A 19540225 - TANTON COMPANY
- [DY] US 6041828 A 20000328 - BAUKLOH ACHIM [DE], et al
- [Y] US 2434855 A 19480120 - TERAN KOSTERLITZKY JOSE L
- [Y] US 2072229 A 19370302 - LOUIE WAITMAN
- [A] PATENT ABSTRACTS OF JAPAN vol. 0050, no. 71 (C - 054) 13 May 1981 (1981-05-13)

Designated contracting state (EPC)

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**EP 1571235 A2 20050907**; **EP 1571235 A3 20080319**; **EP 1571235 B1 20190717**; FR 2867198 A1 20050909; FR 2867198 B1 20070914

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